

ABSTRACT

The invention provides arrangements to facilitate surface mounting of subassembly boards on a motherboard with reliable, high conductivity interconnection. In accordance with the invention, the subassembly interconnection arrangement is composed of separate power and sense connector arms formed on one or more base headers. The arrangement interconnects and supports the subassembly board on the motherboard surface. Each power arm advantageously comprises a plurality of split-based mounting lugs secured to the arm in a coplanar configuration. Each sense connector arm preferably comprises a plurality of connector pins secured to the arm in a coplanar configuration. Embodiments are disclosed for vertical and horizontal surface mounting.